

What Is Claimed Is:

1. A surface-mount crystal oscillator comprising:
    - a casing having a recess defined therein;
    - a crystal blank fixedly mounted on a bottom of said recess; and
    - an IC chip having an integrated oscillating circuit connected to said
- 5 crystal blank;
- said casing having a frame wall which defines said recess, said IC chip having an outer peripheral edge joined to an upper surface of said frame wall, said crystal blank being hermetically sealed in a space surrounded by said casing and said IC chip.
2. The surface-mount crystal oscillator according to claim 1, wherein said IC chip is joined to the upper surface of said frame wall by an adhesive.
  3. The surface-mount crystal oscillator according to claim 1, further comprising:
    - IC terminals disposed on one principal surface of said IC chip; and
    - IC connecting terminals disposed on the upper surface of said frame
- 5 wall;
- said IC chip having the other principal surface which is joined to an inner peripheral edge of the upper surface of said frame wall, said IC terminals and said IC connecting terminals being electrically connected to each other with wires by wire bonding.

4. The surface-mount crystal oscillator according to claim 3, further comprising a resin layer disposed at least along the outer peripheral edge of said IC chip in covering relation to said IC connecting terminals and the wires by wire bonding.

5. The surface-mount crystal oscillator according to claim 4, further comprising a second frame wall mounted on the upper surface of said frame wall, said resin layer being formed by pouring a resin liquid into a space defined within said second frame wall.

6. The surface-mount crystal oscillator according to claim 2, further comprising:

IC terminals disposed on one principal surface of said IC chip; and

IC connecting terminals disposed on the upper surface of said frame

5 wall;

said adhesive comprising an anisotropic electrically conductive adhesive, said IC terminals and said IC connecting terminals being electrically connected to each other by said anisotropic electrically conductive adhesive with said one principal surface facing the bottom of said recess.

7. The surface-mount crystal oscillator according to claim 6, further comprising a resin layer disposed on at least the upper surface of said frame wall along the outer peripheral edge of said IC chip.

8. The surface-mount crystal oscillator according to claim 1, wherein said casing is made of ceramic.